

(0.635 mm) .025"

QMS SERIES

RUGGED GROUND PLANE HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer

Terminal & Ground

Plane Material:

Phosphor Bronze

Plating:

Au over 50 μ " (1.27 μ m) Ni

(Tin on Ground Plane Tail)

Current Rating:

Contact:

2.6 A per pin

(2 pins powered)

Ground Plane:

15.7 A per ground plane

(1 ground plane powered)

Operating Temp:

-55 °C to +125 °C

Voltage Rating:

300 VAC mated with QFS

RoHS Compliant:

Yes

Board Mates:

QFS

Cable Mates:

6QCD

Standoffs:

SO, JSOM

ALSO AVAILABLE (MOQ Required)

- Other platings
- Guide Posts
- Without PCB Alignment Pins (05.75 and 06.75 only)
- Hot Pluggable
- 64 (-DP) and 104 positions per row

HIGH-SPEED CHANNEL PERFORMANCE

QMS-DP/QFS-DP @ 10 mm Mated Stack Height

Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com
or contact SIG@samtec.com

25
Gbps

Integral metal plane
for power or ground

Increased
insertion depth for
rugged applications

(1.60 mm)
.063"
NOMINAL
WIPE

POWER/SIGNAL APPLICATION

Compatible with
UMPT/UMPS for flexible
two-piece power/signal solutions

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (026-052)

(0.15 mm) .006" max (078)*

*(.004" stencil solution

may be available; contact

IPG@samtec.com)

Board Stacking:

For applications requiring more
than two connectors per board,
contact ipg@samtec.com

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality



STANDARDS

- SUMIT™
- PCI/104-Express™
- PCI/104-Express™ OneBank

Visit www.samtec.com/standards
for more information.

Note:

Some lengths, styles and
options are non-standard,
non-returnable.

QMS	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank = -D) -016, -032, -048 (16 pairs per bank = -D-DP) (-078 & -048 Not available with -09.75 lead style)	Specify LEAD STYLE from chart	-L (-05.75 and -06.75 lead style only) = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails) -SL (-09.75 lead style only) = 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane (Tin on Signal Pin tails, and Ground Plane tails)	-D = Single-Ended -D-DP = Differential Pair		-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad

Diagram showing dimensions for the connector top view.

Diagram showing dimensions for the connector side view.

Diagram showing dimensions for the connector side view.

Diagram showing dimensions for the connector side view.

APPLICATION

Requires Standoff
SO-1524-03-01-01-L or
JSOM-1524-02 for 15.24 mm
or SO-2215-02-01-01-L for 22 mm
board spacing. Connectors designed
to not fully seat when mated.

MATED HEIGHT*			
LEAD STYLE	A	QFS LEAD STYLE	
		-04.25	-06.25
-05.75	(5.38) .212	10 mm	12 mm
-06.75	(6.35) .250	11 mm	13 mm
-09.75	(9.35) .368	14 mm	16 mm

*Processing conditions will affect mated height.
See SO Series for board space tolerances.

INDUSTRY STANDARD	INTERCONNECTS			
	TERMINAL	SOCKET	BANKS	STACK HEIGHT
SUMIT™	ASP-129637-01	ASP-129646-01	1	15.24 mm
PCI/104-Express™	ASP-129637-03	ASP-129646-03	3	15.24 mm
PCI/104-Express™	ASP-129637-13	ASP-129646-22	1	15.24 mm
PCI/104-Express™	ASP-142781-01	ASP-129646-01	1	22 mm
PCI/104-Express™	ASP-142781-02	ASP-129646-02	2	22 mm
PCI/104-Express™	ASP-142781-03	ASP-129646-03	3	22 mm

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.